

# **WHM200A**

P/N: WSWHM200A00

DATA SHEET / REV0.31

SJIT Co.,Ltd

54-11, Dongtanhana 1-gil, Hwaseong-si, Gyeonggi-do, South Korea

http://sjit.company

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### Aim of this Document

The aim of this document is to give a detailed product description including interfaces, features and performance of the module WHM200A.

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#### 1. Introduction

The WHM200A uses the new Wi-Fi standard IEEE 802.11ah, which uses the Sub 1 GHz license-exempt band. It has long range, low power and high permeability and is optimized for IoT modules.

The WHM200A includes a RF switch and an internal PA in the SoC to increase transmit power up to 28dBm.



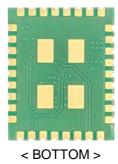


Figure 1-1: Picture of WHM200A

#### 1.1 Key Features

- Compact module 14 x 17.5 x 2.8mm. (Typ.)
- Full IEEE 802.11ah compatibility with enhanced performance
- AP and STA, mesh network support
- UART and SPI support for host interface
- Low-Power Long Range Transceiver operating in the sub-1GHz ISM band
- RF interface optimized to 50  $\Omega$ .
- Output Power Level up to +28dBm (MCS10)
- -107 dBm minimum receive sensitivity (MCS10)

#### 1.2 Applications

- Smart home and home security
- Smart factory and factory automation
- Smart city and public transportation management
- Smart grid/metering
- Surveillance camera and remote monitoring of wildlife
- Wireless sensor network
- Health care
- Electric vehicle and charging
- Commercial drone
- Wireless Alarm and Security Systems.

### 2. Description

The WHM200A is a long range, high-performance module for wireless communication. The module is solder-able like a SMD component and can easily be mounted on a simple carrier board with a minimum of required external connections.

It includes all necessary passive components for wireless communication as depicted in the following figure.

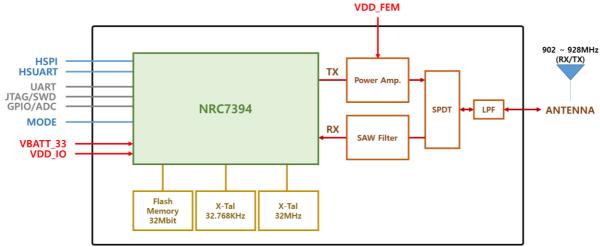


Figure 2-1: Block Diagram

#### 2.1 CPU

- ARM® Cortex-M3 for IEEE 802.11ah WLAN and application
- Clock frequencies for processor(Max 32MHz)

#### 2.2 Memory

- CPU Internal Memory
  - ▲ 32KB Boot ROM
  - ▲ 1,088KB system SRAM
  - ▲ 192KB Key Memory for security
  - ▲ 16KB cache for XIP
- CPU External Memory
  - ▲ 32Mbit Flash Memory

### 3. Electrical Characteristics

In the following different electrical characteristics of the WHM200A are listed.

 Note: Stress exceeding of one or more of the limiting values listed under "Absolute Maximum Ratings" may cause permanent damage to the radio module

### 3.1 Absolute Maximum Ratings

Paramete	er	Min	Max	Unit
Storage Tempe	erature	-40	+125	°C
Supply Voltage	VBATT	-0.5	3.8	V
	VDD_IO	-0.5	3.8	V
	VDD_FEM	-0.5	3.8	V

Table 3-1-1: Absolute Maximum Ratings

### 3.2 Recommended Operating Condition

Parameter	r	Min	Тур	Max	Unit
Operating temperat	ure range	-40	-	+85	℃
	VBATT	2.4	3.3	3.6	V
Operating Voltage	VDD_IO	1.68	3.3	3.6	V
	VDD_FEM	3.0	3.3	4.5	V
	VBATT	170			mA
Operating current (peak) Tx @1M/MCS10/27dBm	VDD_IO	2			mA
	VDD_FEM	800			mA
Operation Clock	Transceiver		32		MHz
Frequency	MCU RTC		32.768		kHz

Table 3-2-1: Operating Condition

## 3.3 Electrical Specification

MODE	DUT Status	VDD_IO (mA)	VBATT (mA)	VDD_FEM (mA)
	Tx @ 0 dBm	1.0	94	110
	Tx @ 10 dBm	1.0	99	141
902 11ab	Tx @ 15 dBm	1.0	101	182
802.11ah	Tx @ 20 dBm	1.0	120	300
	Tx @ 25 dBm	1.0	142	471
	Continuous Rx @ -85 dBm	2	25	-

Notes:

Unless otherwise specified, TA.=25°C, VBATT= 3.3V, Continuous Mode, 1M, MCS0, 915.5MHz

Table 3-3-1: Current Consumption

#### 3.4 RF Characteristics

## 3.4.1 Transmitter(Max Power by Country Code)

Country Code	BandWidth	CF	Max Power	USE
	1 MHz	902.5 MHz	-	Not Use
	1 MHz	903.5 MHz	23dBm ± 2dB	USE
	1 MHz	904.5 MHz	23dBm ± 2dB	USE
	1 MHz	905.5 MHz	23dBm ± 2dB	USE
	1 MHz	906.5 MHz	23dBm ± 2dB	USE
	1 MHz	907.5 MHz	23dBm ± 2dB	USE
	1 MHz	908.5 MHz	23dBm ± 2dB	USE
	1 MHz	909.5 MHz	23dBm ± 2dB	USE
	1 MHz	910.5 MHz	23dBm ± 2dB	USE
	1 MHz	911.5 MHz	23dBm ± 2dB	USE
	1 MHz	912.5 MHz	23dBm ± 2dB	USE
	1 MHz	913.5 MHz	23dBm ± 2dB	USE
	1 MHz	914.5 MHz	23dBm ± 2dB	USE
	1 MHz	915.5 MHz	23dBm ± 2dB	USE
	1 MHz	916.5 MHz	23dBm ± 2dB	USE
	1 MHz	917.5 MHz	23dBm ± 2dB	USE
	1 MHz	918.5 MHz	23dBm ± 2dB	USE
	1 MHz	919.5 MHz	23dBm ± 2dB	USE
	1 MHz	920.5 MHz	23dBm ± 2dB	USE
	1 MHz	921.5 MHz	23dBm ± 2dB	USE
	1 MHz	922.5 MHz	23dBm ± 2dB	USE
	1 MHz	923.5 MHz	23dBm ± 2dB	USE
US	1 MHz	924.5 MHz	23dBm ± 2dB	USE
	1 MHz	925.5 MHz	23dBm ± 2dB	USE
	1 MHz	926.5 MHz	23dBm ± 2dB	USE
	1 MHz	927.5 MHz	-	Not Use
	2 MHz	903.0 MHz	- 00 dD - 0 dD	Not Use
	2 MHz	905.0 MHz	23dBm ± 2dB	USE
	2 MHz	907.0 MHz	23dBm ± 2dB	USE
	2 MHz	909.0 MHz	23dBm ± 2dB	USE
	2 MHz	911.0 MHz	23dBm ± 2dB	USE
	2 MHz	913.0 MHz	23dBm ± 2dB	USE
	2 MHz	915.0 MHz	23dBm ± 2dB	USE
	2 MHz	917.0 MHz	23dBm ± 2dB	
	2 MHz	919.0 MHz	23dBm ± 2dB	USE
	2 MHz	921.0 MHz	23dBm ± 2dB	USE
	2 MHz	923.0 MHz	23dBm ± 2dB 23dBm ± 2dB	USE
	2 MHz	925.0 MHz	ZOUDIII ± ZUD	
	2 MHz	927.0 MHz	- 21dBm ± 2dB	Not Use
	4 MHz	906.0 MHz	23dBm ± 2dB	USE USE
	4 MHz	910.0 MHz	23dBm ± 2dB	USE
	4 MHz	914.0 MHz	23dBm ± 2dB	USE
	4 MHz	918.0 MHz	23dBm ± 2dB	USE
	4 MHz	922.0 MHz	ZOUDIII ± ZUD	
	4 MHz	926.0 MHz	<u>-</u>	Not Use

Table 3-4-1-1: Technical Regulations.

#### 3.4.2 Transmitter

Donal	BW	MCS	Modulation/	EVM spec	Max. Power [dBm]		
Band	BW	MICS	Coding Rate	[dB]	VDD_FEM 3.3V	VDD_FEM 4.5V	
		10	BPSK 1/2 rep. 2x	-4	28	28	
		0	BPSK 1/2	-5	28	28	
		1	QPSK 1/2	-10	28	28	
		2	QPSK 3/4	-13	28	28	
	1 MHz	3	16QAM 1/2	-16	27	27	
		4	16QAM 3/4	-19	27	27	
		5	64QAM 2/3	-22	26	26	
		6	64QAM 3/4	-25	24	25	
		7	64QAM 5/6	-27	22	23	
		0	BPSK 1/2	-5	28	28	
		1	QPSK 1/2	-10	28	28	
902		2	QPSK 3/4	-13	28	28	
928	0.1411	3	16QAM 1/2	-16	27	27	
MHz	2 MHz	4	16QAM 3/4	-19	26	27	
		5	64QAM 2/3	-22	25	26	
		6	64QAM 3/4	-25	24	25	
		7	64QAM 5/6	-27	24	24	
		0	BPSK 1/2	-5	29	29	
		1	QPSK 1/2	-10	29	29	
		2	QPSK 3/4	-13	28	29	
	4 8411	3	16QAM 1/2	-16	27	28	
	4 MHz	4	16QAM 3/4	-19	27	27	
		5	64QAM 2/3	-22	26	26	
		6	64QAM 3/4	-25	25	26	
		7	64QAM 5/6	-27	25	26	
ж т	= 25°C,	if nothing el	se stated	1	1		

Table 3-4-2-1: Transmitter(Module's Max Power)

## 3.4.3 Receive Sensitivity

BW	MCS	Modulation	11ah spec	Min. Sensitivity [dBm]			
DVV	IVICS	/ Coding Rate	Trail spec	Min	Тур	Max	
	10	BPSK ½ rep. 2x	-98		-106		
	0	BPSK ½	-95		-103		
	1	QPSK ½	-92		-102		
	2	QPSK ¾	-90		-100		
1 MHz	3	16QAM ½	-87		-97		
	4	16QAM ¾	-83		-94		
	5	64QAM <sup>2</sup> / <sub>3</sub>	-79		-89		
	6	64QAM ¾	-78		-88		
	7	64QAM 5/6	-77		-87		
	0	BPSK ½	-92		-100		
	1	QPSK ½	-89		-98		
	2	QPSK ¾	-87		-96		
	3	16QAM ½	-84		-93		
2 MHz	4	16QAM ¾	-80		-90		
	5	64QAM ⅔	-76		-86		
	6	64QAM ¾	-75		-83		
	7	64QAM 5/6	-74		-82		
	0	BPSK 1/2	-89		-98		
	1	QPSK 1/2	-86		-95		
	2	QPSK 3/4	-84		-93		
4 85	3	16QAM 1/2	-81		-90		
4 MHz	4	16QAM 3/4	-77		-87		
	5	64QAM 2/3	-73		-83		
	6	64QAM 3/4	-72		-81		
	7	64QAM 5/6	-71	_	-80		

Figure 3-4-3-1: Receive Sensitivity

#### 3.4.4 Output Power vs. Input Voltage(VDD) table

Input Voltage(VDD)	2.4V	2.6V	2.8V	3.0V	3.2V	3.3V	3.6V	3.8V	4.0V	4.2V	4.5V
Output Power (Typ.) / dBm	15.55	19.9	21.4	21.99	22.06	22.15	22.1	22.11	22.04	22.1	22.04

X T = 25°C, MCS7, VDD\_IO=3.3V, 1M Bandwidth, Target Power : 22dB

Table 3-4-4-1: Output Power vs. Input Voltage

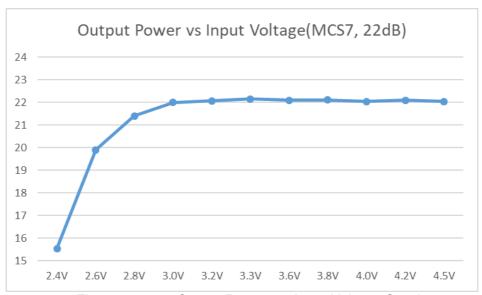


Figure 3-4-4-1: Output Power vs. Input Voltage Graph

### 4. Module Package

In the following the WHM200A module package is described. This description includes the WHM200A pinout as well as the modules dimensions. Furthermore a recommendation for a suitable footprint is given, which should be used for further mounting on appropriate carrier boards.

### 4.1 Pinout Description

Figure 4-1-1 depicts a description of the WHM200A's pads on the bottom side. The figure shows the module with its pinout in top view (right figure). A detailed description of the individual pins can be found in Table 4-1-1: Pinout Table.

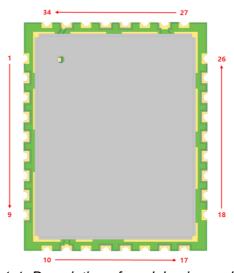


Figure 4-1-1: Description of module pins and top view

Pin No	Name	Direction	Description	GPIO Function
1	GND	GND		
2	UART1_TXD/GP12	0	UART channel1 Tx data	GP12
3	UART1_RXD/GP13	I	UART channel1 Rx data	GP13
4	UART1_CTS/GP14	I	UART channel1 clear to send	GP14
5	UART1_RTS/GP20	0	UART channel1 request to send	GP20
6	Mode/GP19	I	Boot mode (0: ROM boot, 1: XIP boot)	GP19
7	ADC0/GP17	I	Auxiliary ADC channel 0	GP17
8	ADC1/GP18	I	Auxiliary ADC channel 1	GP18
9	GP25	I/O	GPIO	GP25
10	GND	GND		
11	VDD_IO	Р	NRC7394 I/O power input	

12	GND	GND		
13	UART0_RXD/GP09	I	UART channel0 Rx data	GP09
14	UART0_TXD/GP08	0	UART channel0 Tx data	GP08
15	GND	GND		
16	VBATT	Р	NRC7394 PMS, RF/PA power input	
17	PMS_nPOR/nRST	I/O	NRC7394 reset (active low) input, POR reset output (internal pull-up)	
18	GND	GND		
19	HSPI_nCS/GP28	I	Host SPI – chip select (active low)	GP28
20	HSPI_MISO/GP29	0	Host SPI – master in slave out	GP29
21	HSPI_MOSI/GP06	I	Host SPI – master out slave in	GP06
22	HSPI_CLK/GP07	I	Host SPI – clock	GP07
23	HSPI_nEIRQ/GP30	0	Host SPI – interrupt (active low)	GP30
24	SWD_IO/GP10	I/O	SWD data	GP10
25	SWD_CLK/GP11	I	SWD clock	GP11
26	GND	GND		
27	GND	GND		
28	VDD_FEM	Р	Power AMP Power input	
29	GND	GND		
30	NC			
31	NC			
32	GND	GND		
33	RF_ANT	I/O	RF input/output	
34	GND	GND		

Table 4-1-1: Pinout Table

#### 4.2 Module Dimensions

The outer dimensions of the WHM200A are given by Figure 4-2-1.

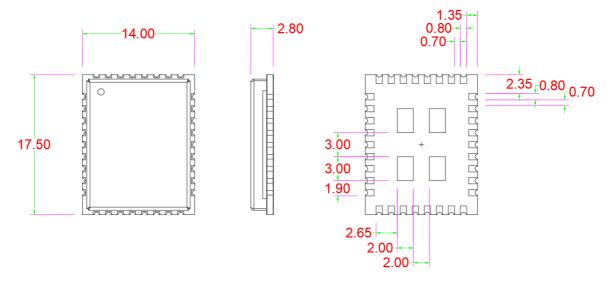


Figure 4-2-1: Outer Dimensions

#### 4.3 Recommended Footprint

According to Chapter 4.2, a recommendation for the footprint of the WHM200A is given by Figure 4-3-1.

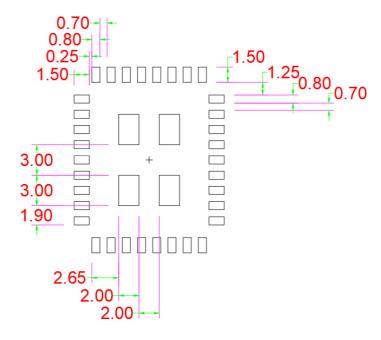


Figure 4-3-1: Recommended footprint (top view)

## 4.4 Recommended PCB design guide

To protect a contact short or electrical shock when WHM200A module is mounted on customer's board, we recommend PSR ink-coating(Green Area) of top side at module mount area on customer's board as Figure 4-4-1.

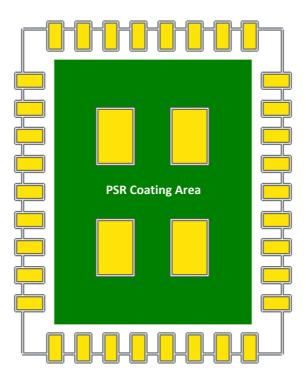
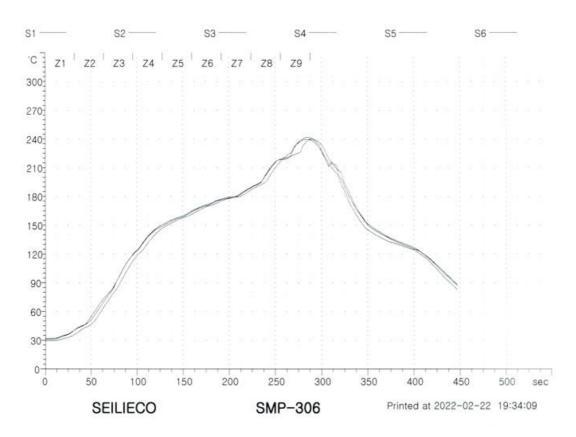


Figure 4-4-1: PSR ink Coating of mount board

#### 4.5 Reflow Profile of Module

		Z1	Z2	Z3	Z4	Z5	Z6	<b>Z</b> 7	Z8	Z9				ne No :		
Upp Lov Len		150 150 400	160 160 400	170 170 400	180 180 400	190 190 400	200 200 400	220 2	250 285 250 285 400 400	285				peed: 0. ength: 3		
_		.10	t-coc	ov-2	978 T	000	T2-s	10.00		2-150	ature Z	Tallacare	's T2-'C/s	T2 10/a	T4_10/a	TE 10/a
	May															
S1 S2 S3 S4 S5	241 0.0 239 0.0 0.0	.7 2	285.5 0.0 283.0 0.0	45.5 0.0 40.5 0.0 0.0	50	66.0 0.0 66.5 0.0	83.5 0.0 84.5 0.0 0.0	66 0.0 65 0.0	.5	45.5 0.0 40.5 0.0 0.0	75-s 0.0 0.0 0.0 0.0 0.0	+1.1 +0.0 +1.1 +0.0 +0.0	+0.7 +0.0 +0.7 +0.0 +0.0 +0.0	+0.5 +0.0 +0.5 +0.0 +0.0	+0.2 +0.0 +0.2 +0.0 +0.0 +0.0	+0.0 +0.0 +0.0 +0.0 +0.0 +0.0



	Pre-heat	Soak	Ramp	PEAK
SPEC	50~100'C	100~170'C	220'C 이상	240'C
	1~2'C/sec	60~100 sec	30~50 sec	±5'C
Result	1.13	84	44.3	239.4
	ок	ок	ок	ок

## 5. Integration Guide

The WHM200A provides 34 connectors as described in Chapter 5. For integrating the WHM200A into an environment, a typically circuit as given in Chapter 5.1 can be used.

#### 5.1 Mode Pin Setting

MODE pin is provided for boot mode selection to offer flexible and configurable boot options as shown in Table below

In the case of XIP boot, it is necessary to change to XIP boot mode after FW upload, so users need to install a switch that can control the mode pins on the board

MODE pin	Description
VDD	XIP boot mode  Firmware must be downloaded to external flash memory before power on.  The start address for boot is remapped to the start address of flash memory.
GND	ROM boot mode  Boot from internal ROM code and wait for external command via HSPI or UART. The start address for boot is remapped to the start address of ROM memory.
GND	FW upload mode  Firmware upgrade to external flash memory or upload to internal SRAM via UART0.

## 5.2 Typical Application Schematic

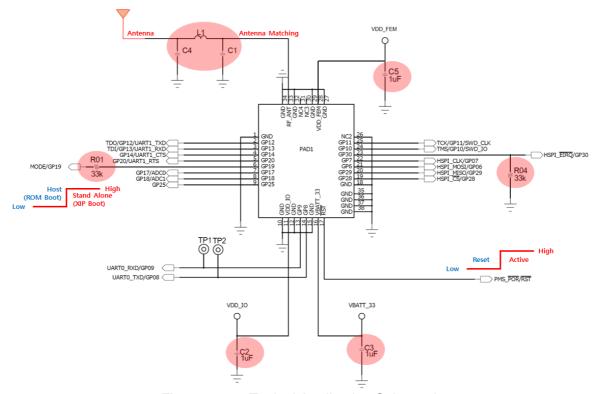


Figure 5-2-1: Typical Application Schematic

## 6. Laser Marking



FCC ID
--------

<sup>&</sup>quot;This Module may cause radio interference while in use and may cause harmful interference from other devices"

#### WHM200A Lot, No(9digits) Information

W	A	K	A	V	2	0	0	1
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

No.				E	XPLANA	ATION							
2	Blue Too	ue Tooth( <b>B</b> ), Wi-Fi( <b>W</b> ), Zigbee( <b>Z</b> ), Combo( <b>C</b> ) , NFC( <b>N</b> )											
2		ture Area king Lot Area	a	A Korea	С	B hina	C Vietn	am					
	Year								1				
3	Year	2021	2022	2023	2024	2025	2026	2027					
	Mark	Н	I	J	K	K L		N					

	Month														
4	Month	1	2	3	4	5	6	6 7	7 8	3	9	10	11	12	
	Mark	A	В	С	D	Е	F	= 0	}  -	ł	I	J	K	L	
	Day														
	Day	1	2	3	4	5	,	6	7	8	3	9	10		
	Mark	1	2	3	4	5		6	7	8	3	9	Α		
(5)	Day	11	12	13	14	15	5	16	17	18	8	19	20		
	Mark	В	С	D	Е	F		G	Н	ı		J	K		
	Day	21	22	23	24	2	5	26	27	2	8	29	30	31	
	Mark	L	М	N	0	Р	)	Q	R	S	3	Т	U	V	
67	Model Ser	Model Serial Number (WHM200A : US High Power)													
89	89 A Serial Number(1serial: 1Box)														

#### WHM200A QR-code(44digits) Information



← ex) 200AXK1ER01000001G,88571DF1AD1D,88571DF1AD1F

Digits	QR code info	Description
1~18	Serial(Lot) No.	200AXK1ER01000001G
19	,	Comma
20~31	WIFI MAC0	Mac Address 12digits
32	,	Comma
33~44	WIFI MAC1	Mac Address 12digits

#### Serial No.

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
Model	M	ODEL	COD	E	ASSY	YEAR	Month	Day	HW	/ vers	ion	SW App.	SW Ver.	SEI	RIALI	NUME	ER	Customer
WHM200A	2	0	0	Α	Х	K	1	E	R	0	1	0	0	0	0	0	1	G

## 7. Packing

## 7.1 Reel Packing

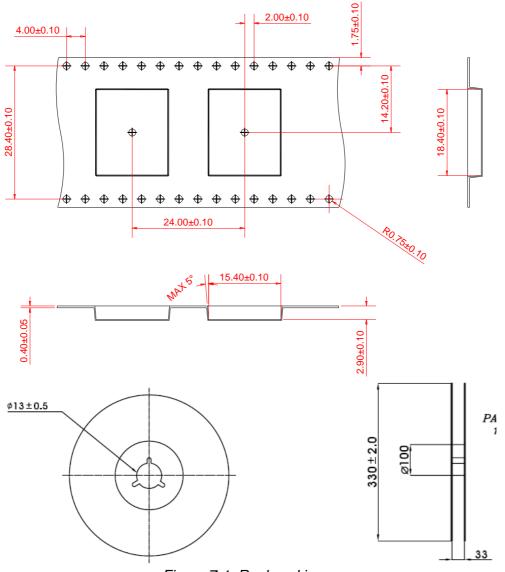


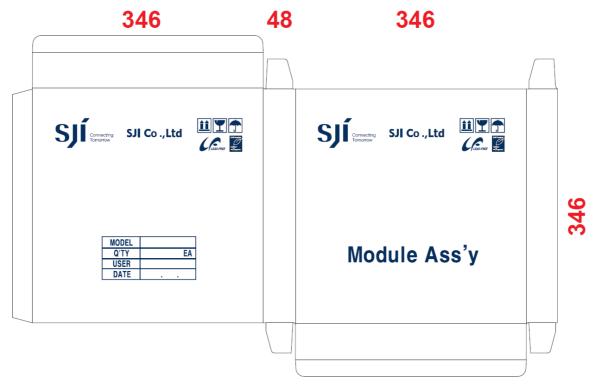
Figure 7-1: Reel packing

<sup>\*</sup> Reel Bobbin size: 15.4 x 18.4 X 2.9mm(480pcs/Reel)

<sup>\*</sup> Packing Q'ty: 2,400pcs/Box

## 7.2 Packing Box

- Inner Box : 346 X 18 X 346 mm



- Out Box : 365 X 270 X 365 mm

365 270 365 270

SJÍ CO.,Ltd SJÍ C

# 7.2 Packing Bag & Silica Gel





Aluminum Bag

Silica Gel(20g)

#### 8. Notice

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# **ESD Warning**



This modules are ESD sensitive devices, appropriate precautions should be taken during the module assembly in the final product.

Mechanical impact and harsh tools must be avoided during the module assembly in the final product.

#### Product ESD specification:

▲ HBM ±2kV

The following precautions must be taken:

- ▲ Do not open the protective conductive packaging until you have use the following, and are at an approved anti-static work station.
- ▲ Use a conductive wrist strap attached to a good earth ground.
- ▲ If working on a prototyping board, use a soldering iron or station that is marked as ESD-safe.
- ▲ Use an approved anti-static mat to cover your work surface.